# **BGA Heat Sink - High Performance Device Specific - NXP**





\*Image above is for illustration purpose only.

ATS Part#: ATS-59004-C1-R0

Description: 32.00 x 50.00 x 12.00 mm BGA Heat Sink - High Performance Device Specific - NXP

Heat Sink Type: NXP
Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-59004-C2-R0 Discontinued

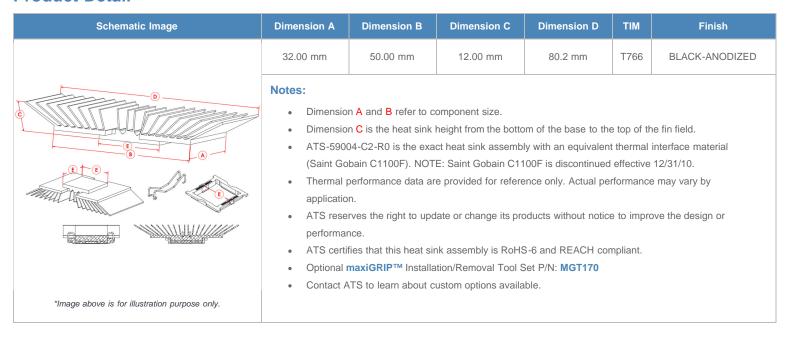
### **Features & Benefits**

- Designed for flip-chip processors such as NXP MPCs
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- · Comes preassembled with high performance, phase changing, thermal interface material

#### **Thermal Performance**

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.2 °C/W	2.46 °C/W	2 °C/W	1.7 °C/W	1.5 °C/W	1.3 °C/W	1.2 °C/W
	Ducted Flow	1.9	N/A	N/A	N/A	N/A	N/A	N/A

#### **Product Detail**







## **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Heat Sinks category:

Click to view products by Advanced Thermal Solutions manufacturer:

Other Similar products are found below:

581102B00000G 656-15ABPE 657-20ABPNE 7020B-TC12-MTG 73452PPBA 7G0011A PF720G A22-4026 120-1873-007 HAH10L HAH15L 1542616-1 HS-2506-F1 HS-87M0-F2 218-40CTE3 231-69PAB-15V 25-7520 SW50-4G 231-75PAB-13V 231-75PAB-15V 253-122ABE-22 PSC22CB HAF10L HAQ10T D10100-28 BDN183CBA01 3-21053-4 32438 TX0506-1B TX1806B LAE66A3CB WA-DT2-101E 511-3U 73381PPBA 73403PPBA 7G0047C COMX-440-HSP 510-12M D10650-40T5 V8511 Y APF40-40-13CB/A01 780653U04500G ATS-54310K-C2-R0 FK 216 CB SA FK 231 SA 220 648-51AB 657-20ABPESC 2341BG 679-25AG FK 212 CB SA